

基板取付穴推奨寸法 (参考) (t=1.6)  
RECOMMENDED P.C. BOARD HOLE DIM. (REF.)

注記 NOTES

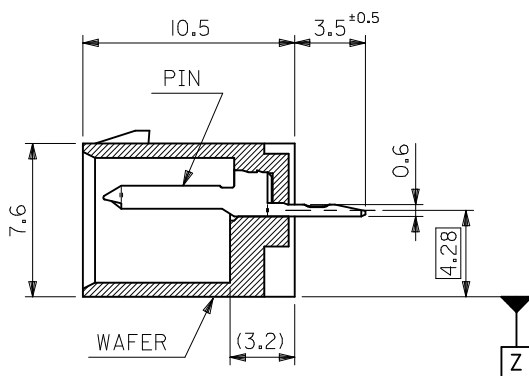
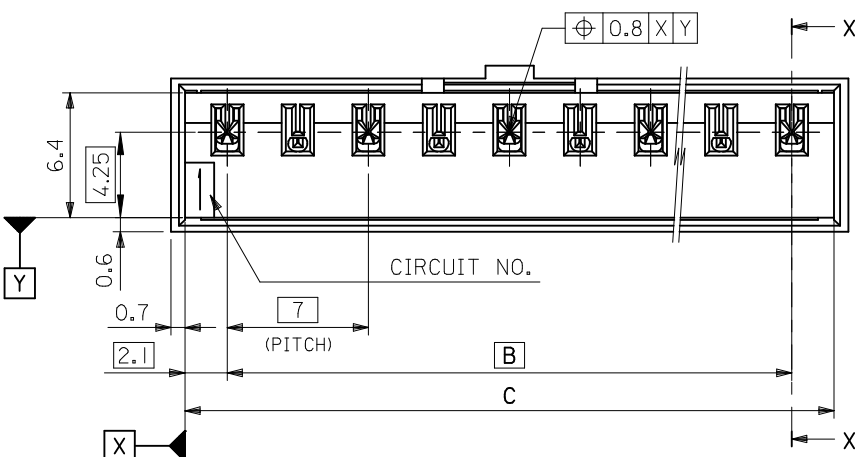
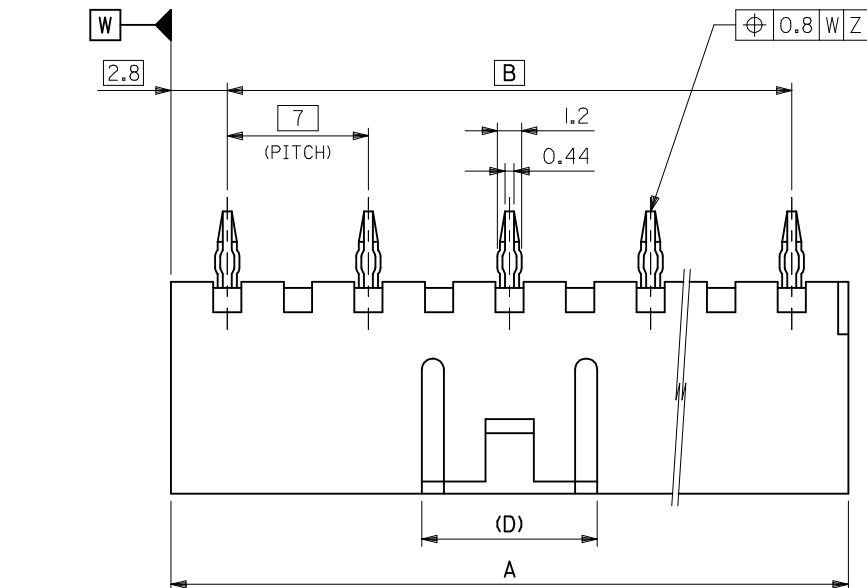
1. 嵌合相手: 51067 シリーズ  
MATE WITH : 51067 SERIES
2. 材質  
MATERIAL  
ウエハー: PBTP (ガラス15%入り)、UL94V-0  
WAFER: PBTP (G.F 15%), UL94V-0  
ピン: リン青銅、ニッケル下地 鍍メッキ(+0.254)  
PIN: PHOSPHOR BRONZE  
TIN OVER NICKEL PLATING (+0.254)
- △ 製品番号の末尾は製品の色を示す。  
COLOR OF WAFER  
CORRESPONDS TO LAST DIGIT OF MATERIAL NO.  
白: WHITE : 53265-\*\*\*80  
黒: BLACK : 53265-\*\*\*81  
赤: RED : 53265-\*\*\*82  
黄: YELLOW : 53265-\*\*\*83  
青: BLUE : 53265-\*\*\*84
4. 本製品は 53265-\*\*\*1\* の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53265-\*\*\*1\*.

8.7	53.2	49.0	54.6	53265-088*	8
8.7	18.2	14.0	19.6	53265-038*	3
6.1	11.2	7.0	12.6	53265-028*	2
(D)	C	B	A	TRAY PACKAGE	CKT.
				△ ORDER No. オ-ダ-番	

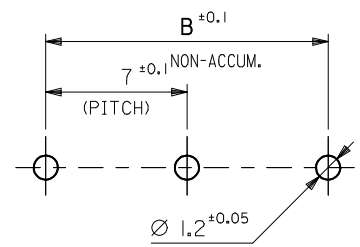
REVISED EC NO: J2017-0224 DRWN: MISHIKAWA 2016/10/12 CHKD: TAKAHASHI 2016/10/12 APPR: MSASAO 2016/10/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4:1	MODEL NO. 53265-***8*
	0.25 UNDER	UNDER	±	DRAWN BY T. UENO	DATE '04/04/13	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASSY ST. -LEAD FREE- <b>molex</b> DOCUMENT NO. SD-53265-003 SHEET NO. 1 OF 1
	0.25 OVER	0.5 UNDER	±	CHECKED BY M. SASAO	DATE '04/04/13	
	0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO	DATE '04/04/13	
	0	OVER 10 UNDER	±0.2	MATERIAL NO.		
10	OVER 30 UNDER	±0.25	SEE TABLE			
30	OVER	±0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
ANGULAR		±3 °	SIZE A3			

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SECT X-X



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	0.25 UNDER	UNDER	±	DRAWN BY T. UENO	DATE '04/04/13	TITLE 7.0 WIRE TO BOARD CONN. WAFER ASSY ST. -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±	CHECKED BY M. SASAO	DATE '04/04/13		
	0.5 OVER	1.0 UNDER	±	APPROVED BY M. SASAO	DATE '04/04/13		
	0	OVER 10	UNDER	±0.2	MATERIAL NO.		DOCUMENT NO. SD-53265-003
10	OVER 30	UNDER	±0.25	SEE TABLE			
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ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				